

ABSTRACT

More compact, thinner, shorter and lighter surface-mounted electronic component modules and their manufacturing methods at low costs, thus making them 5 industrially highly valuable are available. Such the component includes a wiring substrate having wiring patterns formed on one side and external connection terminals formed on the other side, the wiring patterns and the external connection terminals being connected with 10 each other by via holes or through holes; a plurality of electronic component devices mounted on the one side of the wiring substrate; and an exterior resin layer formed on the wiring substrate which covers the plurality of electronic component devices, wherein at least one of the 15 plurality of electronic component devices is fastened face up to the one side of the wiring substrate, the connection terminal of the electronic component device fastened face up and the wiring pattern or the connection terminal of another electronic component device being connected with 20 each other by wire.